

UL - TBD

Isola offers a 370HRN family of no-flow and low-flow prepregs consisting of proprietary resin systems specifically formulated for optimal performance in bonding applications requiring minimal resin flow and consistency in lamination.

PRODUCT FEATURES

Industry Recognition

- UL File Number: E41625
- RoHS Compliant
- Lead-free assembly compatible

Processing Advantages

No-flow Prepreg

- Adhesion to wide range of materials
- Flex films – (Mylar®, Kapton®, etc.)
- Treated or untreated copper
- Plated metals (tin, solder, nickel, etc.)
- Conventional laminate surfaces

PRODUCT AVAILABILITY

Standard Material Offering: Prepreg

- Roll or panel form
- Tooling of prepreg panels

Glass Fabric Availability

- E-glass

370HRN products bring the fabricator specific thermal characteristics appropriate for use in multilayer rigid-flex applications.

PRODUCT ATTRIBUTES



ORDERING INFORMATION:

Contact your local sales representative or contact info@isola-group.com for further information.

Isola Group

6565 West Frye Road Chandler,
AZ 85226 Phone: 480-893-6527
Fax: 480-893-1409

Isola Asia Pacific

(Hong Kong) Ltd. 12/F,
Kin Sang Commercial Centre,
49 King Yip Street, Kwun Tong,
Kowloon,
Hong Kong Phone: 852-2418-1318
Fax: 852-2418-1533

Isola GmbH

Isola Strasse 2 D-52348 Düren,
Germany Phone: 49-2421-8080
Fax: 49-2421-808164

Typical Values Table

Property		Typical Value	Units	Test Method
			Metric (English)	IPC-TM-650 (or as noted)
Pressed Thickness	A. 106 B. 1080 C. 1080	0.049 (1.9) 0.064 (2.5) 0.076 (3.0)	mm (mil)	—
Resin Content	A. 106 B. 1080 C. 1080	71 ±2 60 ±2 65 ±2	%	—
Modified Circle Flow	A. 106 B. 1080 C. 1080	0.4 - 1.6 (15.7 - 63) / 1.6 - 3.0 (63 - 118) 0.4 - 1.6 (15.7 - 63) 0.4 - 1.6 (15.7 - 63) / 1.6 - 3.0 (63 - 118)	mm (mil)	101-QA-WI-004339
Glass Transition Temperature (Tg) by DSC		180	°C	2.4.25C
Cure Temperature Recommended for Full Cure		188	°C	—
Min. for Functional Bonding		163	°C	—
Z-Axis CTE	Pre-Tg	45	ppm/°C	2.4.24C
X/Y-Axis CTE	Pre-Tg	13/14	ppm/°C	2.4.24C
Thermal Conductivity		0.40	W/m·K	ASTM E1952
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched B. Etched	Pass	Pass Visual	2.4.13.1
Electric Strength (Laminate & laminated prepreg)		53 (1350)	kV/mm (V/mil)	2.5.6.2A
Peel Strength	Standard profile copper >>> After thermal stress	1.23 (7.0)	N/mm (lb/inch)	2.4.8C

NOTES

Revisions:
A: Initial release - 10/25

Isola, the Isola logo, Astra, Chronon, GETEK, I-Fill, IsoDesign, IsoStack, I-Speed, I-Tera, Polyclad, Stratus, TerraGreen, and The Base for Innovation are registered trademarks or trademarks of ISOLA USA Corp. in the United States and in other countries. Copyright © 2021 Isola Group. All rights reserved.